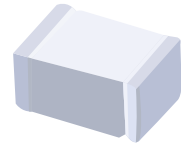
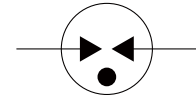


## FEATURES

- | Surface Mounting Design 4.5\*3.2\*2.7mm
- | High Current Handling Capability 2000A @ 8/20 μs
- | Low Capacitance and Insertion Loss
- | Quick Response and Long Service Life
- | Moisture sensitivity level:Level 1



4.5\*3.2\*2.7mm





Schematic Symbol

## APPLICATION INFORMATION

- | Communication equipment.
- | Repeaters,Modems
- | Telephone Interface,Line cards.
- | Data communication equipment.

## AGENCY APPROVALS

Icon	Solderability
RoHS	Compliance with 2011/65/EU
HF	Compliance with IEC61249-2-21:2003
	Mean lead free
	UL Certificated E505857

## PRODUCT CHARACTERISTICS

Lead Material	Body Material	Terminal Finish
Copper or Fe-Ni alloy	Ceramics	100% Matte-Tin Plated

## ELECTRICAL PARAMETER

Parameter	Condition	Rating	Unit
DC Blocking Voltage 1)	100V/s	72-108	V
Impulse Spark-over Voltage	At 1kV/ $\mu$ s	for 99 % of measured values $\leq$ 700	V
	At 1kV/ $\mu$ s	Typical values of distribution $\leq$ 600	V
Impulse Discharge Current 2)	8/20 $\mu$ s	2000	A
Insulation Resistance	DC=50V	$\geq$ 1	G $\Omega$
Capacitance at 1MHz	V <sub>DC</sub> =0.5V	$\leq$ 1.0	pF
Operating And Storage Temperature		-40-125	$^{\circ}$ C

1) In ionized mode

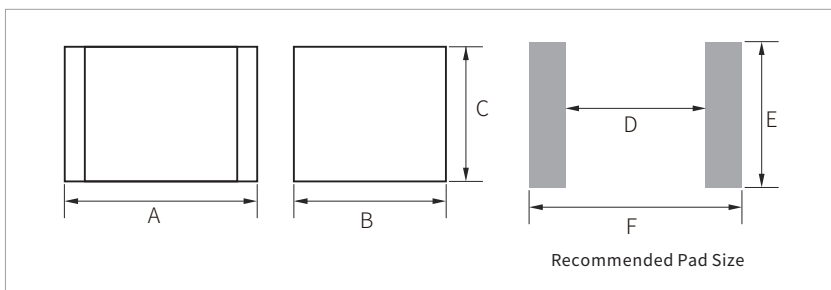
2) Terms and waveforms in accordance with ITU-T Rec. K. 12; IEC 61643-311

## ENVIRONMENTAL RELIABILITY CHARACTERISTICS

Testing items	Technical standards
High Temperature Storage Test	Temperature: 85 $^{\circ}$ C ; Time:2H
Low Temperature Storage Test	Temperature: -40 $^{\circ}$ C ; Time:2H
Vibration	Frequency: 10-500Hz ; Amplitude:0.15mm ; Time:45min
Resistance of soldering heat	Temperature: 260 $\pm$ 5 $^{\circ}$ C; Time of dip soldering: 10s, 1time

**NOTE:**Up-screen program can be specified by customer' s request via contacting Semiware service

## PRODUCT DIMENSIONS AND RECOMMENDED SOLDERING PAD



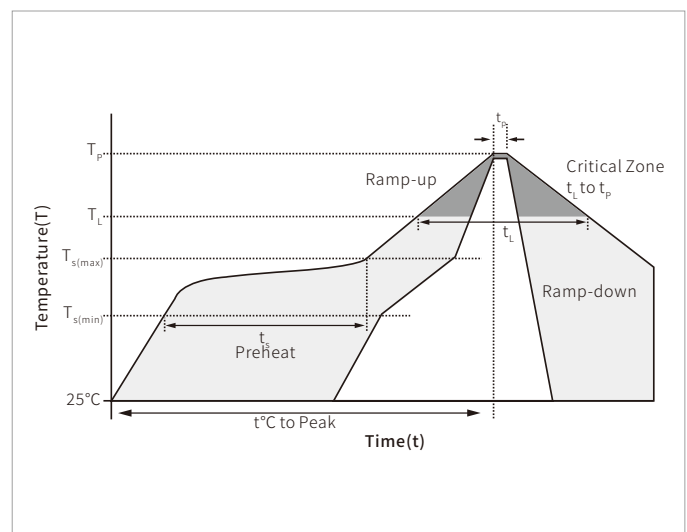
Ref.	mm
A	4.5 $\pm$ 0.3mm
B	3.2 $\pm$ 0.3mm
C	2.7 $\pm$ 0.3mm
D	2.8mm
E	4.0mm
F	5.2mm

## SOLDERABILITY TEST

Solderability	
Solder Pot Temperature	Solder Dwell Time
245°C ± 5°C	4-6 seconds

## REFLOW PROFILE

Reflow Condition		Lead-free assembly
Pre Heat	Temperature Min	150°C
	Temperature Max	200°C
	Time(min to max)	60 – 180 secs
Average ramp up rate (Liquidus)Temp ( $T_L$ ) to peak		3°C/second max
$T_{s(max)}$ to $T_L$ - Ramp-up Rate		
Reflow	Temperature ( $T_L$ ) (Liquidus)	217°C
	Time(min to max)( $t_s$ )	60 – 150 seconds
Peak Temperature ( $T_p$ )		260 °C
Time within 5°C of actual peak Temperature ( $t_p$ )		20-40 seconds
Ramp-down Rate		6°C/second max
Time 25°C to peak Temperature ( $T_p$ )		8 minutes max.
Do not exceed		260°C



## ORDERING INFORMATION

Part Number	Size	QTY/Reel	Reel Size
G4532B090	4.5*3.2*2.7mm	2500PCS	13"

To find your local partner within Semiwell' s website : [www.semiwell.com.cn](http://www.semiwell.com.cn)

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